Title (en)

Method and device for checking the thickness of a liquid metal coating on a filament

Title (de)

Verfahren und Vorrichtung zum Kontrollieren der Dicke einer flüssigen metallischen Schicht auf einem Filament

Title (fr)

Dispositif et procédé pour le contrôle de l'épaisseur d'un revêtement de métal liquide sur un filament métallique

Publication

**EP 0933442 B1 20030409 (FR)**

Application

**EP 98200260 A 19980129**

Priority

EP 98200260 A 19980129

Abstract (en)

[origin: EP0933442A1] A current of gas is directed towards the filament and is coaxial and perpendicular to the filament. The element (5) which directs the gas can be moved to allow replacement with an element having inner diameter determined by the other element as a function of the diameter of the filament to be treated. A device for wiping with a gas jet is designed to control the thickness of coating (1) of liquid metal formed on a metal filament (2) leaving a bath (3) of this liquid metal and being displaced essentially vertically above this bath. The device is arranged at a certain distance above the bath (3) and comprises an element (5) presenting a tubular space (6) with a circular transverse section in which the filament (2) may be axially displaced, an annular injector (7) coaxial to the tubular space (6) directs a current of gas towards the filament in the shape of a blade perpendicular to the axis of the filament and oriented radially with respect to the filament. This allows any excess liquid metal to be wiped from the filament (2) as it leaves the bath (3). The element (5) is mounted so that it can be moved to allow the replacement of an element with an inner diameter determined by another element, as a function of the diameter of the filament to be treated. An Independent claim is also included for the method used to put this wiping device into service.

IPC 1-7

**C23C 2/20**

IPC 8 full level

**C23C 2/20** (2006.01)

CPC (source: EP)

**C23C 2/20** (2013.01)

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**EP 0933442 A1 19990804**; **EP 0933442 B1 20030409**; DE 69813174 D1 20030515; DE 69813174 T2 20040304; TR 199900165 A2 19990823; TR 199900165 A3 19990823; TW 431914 B 20010501

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